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SPARC T5: 16-core CMT Processor with Glueless 1-Hop Scaling to 8-Sockets

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Outline

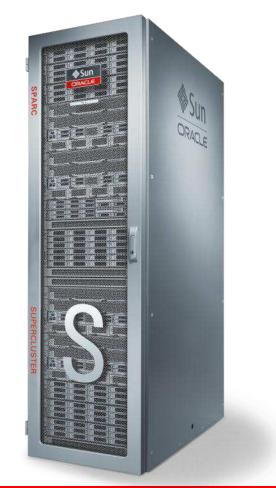
- Design Objectives
- SPARC T5 Processor Overview
- Core S3
- Cache Hierarchy Components
- Internode Coherency for 8-Socket Scaling
- Power Management Advances
- PCI-Express Gen3 I/O Subsystem
- Summary





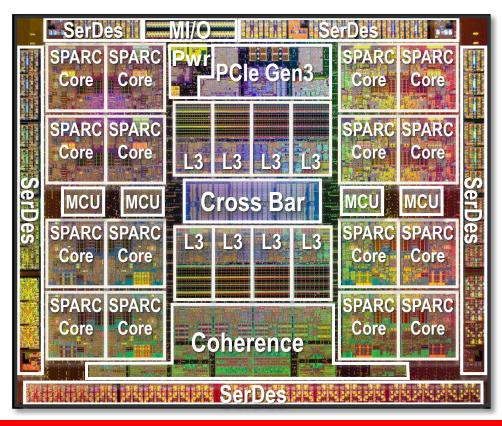
SPARC T5 Design Objectives

- Multiply performance
- Achieve highly efficient 8-socket glueless 1-hop scalability
- Optimize for Oracle workloads and Engineered Systems
- Maximize power efficiency
- Provide Enterprise Class RAS





T5 Processor Overview



- 16 S3 cores @ 3.6GHz
- 8MB shared L3 Cache
- 8 DDR3 BL8 Schedulers providing 80 GB/s BW
- 8-way 1-hop glueless scalability
- Integrated 2x8 PCIe Gen 3
- Advanced Power Management with DVFS

S3 Core Recap

- 28nm port from 40nm T4
- Out-of-order, dual-issue
- High frequency achieved with 3.6GHz
 16 stage integer pipe
- Dynamically threaded, one to eight strands
- Accelerates 16 encryption algorithms and random number generation

SPARC T5 Leads in On-Chip Encryption Acceleration

- Built in, zerooverhead crypto
- Works with Solaris ZFS file system for faster file system encryption
- Provides secure consolidation with dynamic VM migration

On-Chip Accelerators	SPARC T5	IBM Power7	Intel Westmere/ Sandybridge
Asymmetric /Public Key Encryption	RSA, DH, DSA, ECC	none	RSA, ECC
Symmetric Key / Bulk Encryption	AES, DES, 3DES, Camellia, Kasumi	none	AES
Message Digest / Hash Functions	CRC32c, MD5, Sha-1, SHA-224, SHA-256, SHA- 384, SHA-512	none	none
Random Number Generation	Supported	none	Supported



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Core Caches

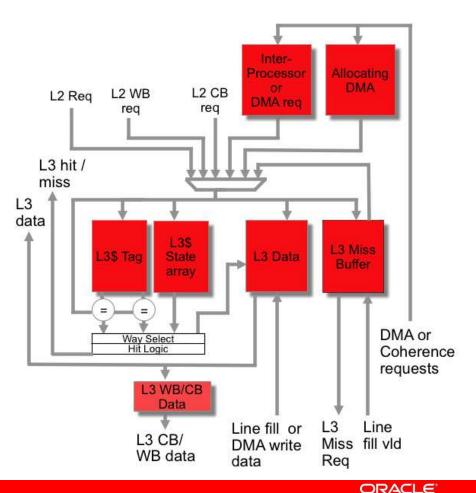
- 16 KB 4-way set associative L1 Instruction cache
- 16 KB 4-way set associative write through L1 Data cache
- 128 KB 8-way set associative, unified, inclusive L2 cache

L2-L3 Interconnect

- 8x9 Crossbar Switch connects the 16 cores to
 - 8 address interleaved address banks and
 - an I/O bridge
- The L3-L2 direction contains a control and data network.
 - control network provides a heads up for dependent instruction wake-up
 - Data network is used to return line fill data and send L3-L2 snoops
- Crossbar network has a bisection BW of 1 TBps, 2x T4

L3 Cache Overview

- 8MB (1MB per bank) 16-way set associative inclusive cache
- MOESI Coherence States per 64B cache line
- Tag results are used to
 - qualify data array access
 - align dependent issue with data return or conditionally flush thread
- Precise tag "reverse" directory keeps L2s coherent



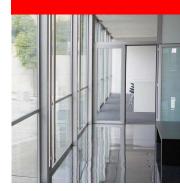
L3 Cache Overview (continued)

- Speeds up IO by allocating DMA buffers in the cache

 Enhances clustered application performance
- Acceleration of contended locks
 - L3 forms a chain of same address requests
 - Processes them atomically on receiving an exclusive copy
- Supports coherent flushing and retirement of cache lines to avoid persistent errors

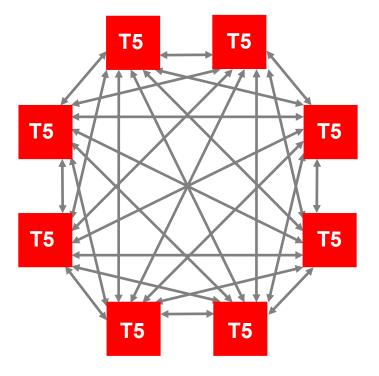
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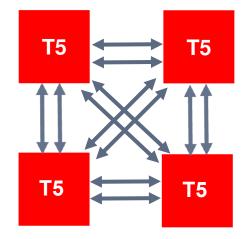
Internode Coherency Overview

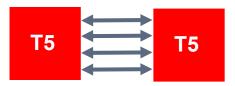
- Glueless 1-hop scaling to eight sockets
- A precise directory tracks all L3s in the system
 - striped across all processors
 - stored in on-chip SRAMs
 - flexible for different socket counts
- Higher BW efficiency than snoopbased protocols enables better scaling
 - 50% more effective bandwidth than comparable snoopy implementation



Internode Coherency Fabric

- Each link is 14 lanes wide and runs up to 15Gbps per lane
- Directly connected links minimize latency
- Trunked links achieve more bandwidth in smaller configurations
- Supports single lane failover

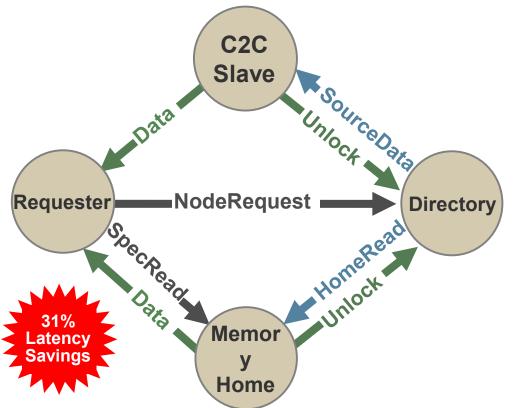




Internode Performance Optimizations

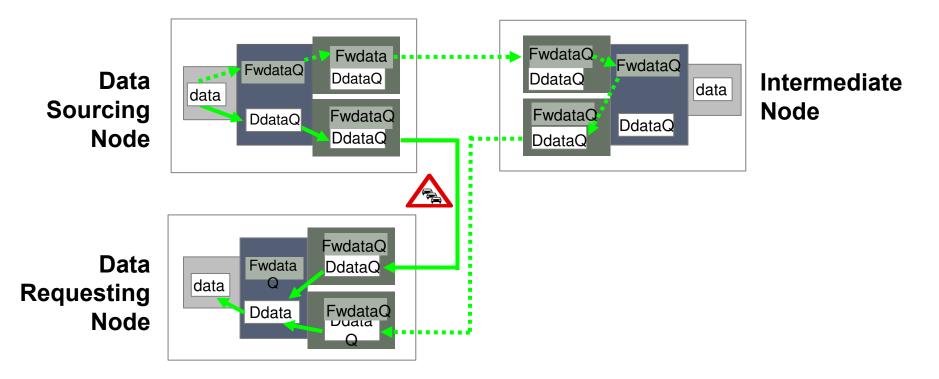
- Speculative memory reads prior to cache line serialization in the directory
- Cache-to-cache line transfers between nodes
- Dynamic congestion avoidance routes inter-node data around congested links

Internode Transaction Flow



- 1. A Requester issues a **NodeRequest** to the Directory and a **SpeculativeRead** to the Memory Home
- 2. After a Directory lookup, either a HomeRead or a SourceData request is generated
- **3. Data** is returned from the Memory Home or C2C Slave

Dynamic Congestion Avoidance



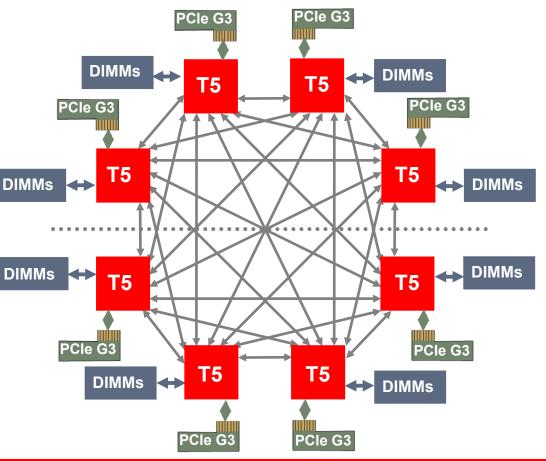


T5-8 Bandwidth

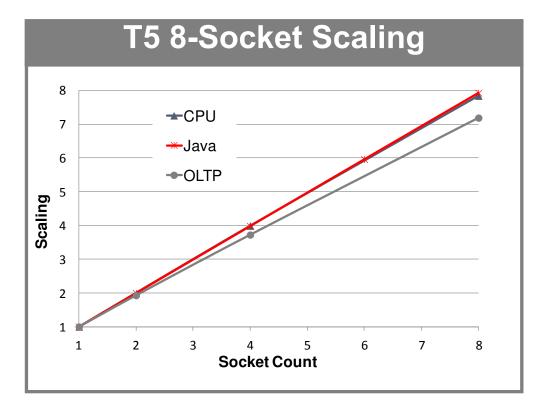
DDR3-1066 1+TB/sec

Coherency Bisection Bandwidth 840 GB/sec

PCI Gen3 Bandwidth 256 GB/sec



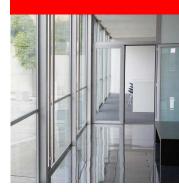
Multiprocessor Performance



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Power Management Advances

- Hardware saves power below 100% utilization with:
 - Chip wide DVFS
 - Per core pair cycle skipping
 - SerDes power scaling
 - DIMM off-lining w/ Dynamic Reconfiguration
 - DRAM PPSE and PPFE support
 - PCI Express Power Management
 - Clock Gating
- When peak performance is demanded
 - Power Management Controller achieves maximum frequency within customer imposed power and thermal limits

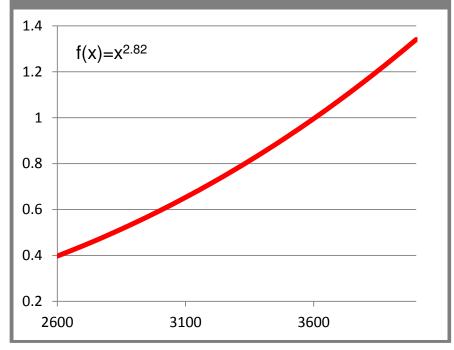


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Power Management Controller: Elastic Savings

- Hardware saves power below 100% utilization
 - Chip wide DVFS
 - Per core pair cycle skipping
- Software monitors frequency needs of all cores
 - Puts chip at DVFS point satisfying all cores requirements
 - Puts core pairs at lowest cycle skip ratio satisfying 2 cores in the pair

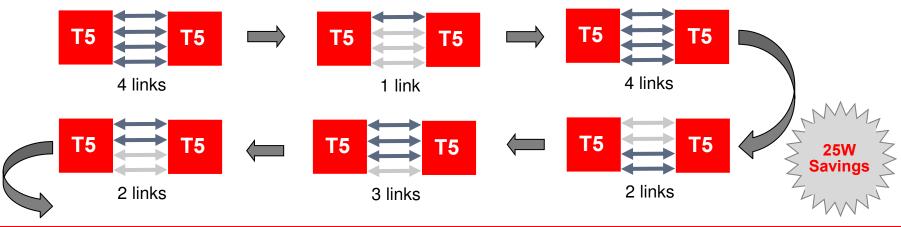
Power vs Frequency with DVFS



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Coherency Link Power Savings

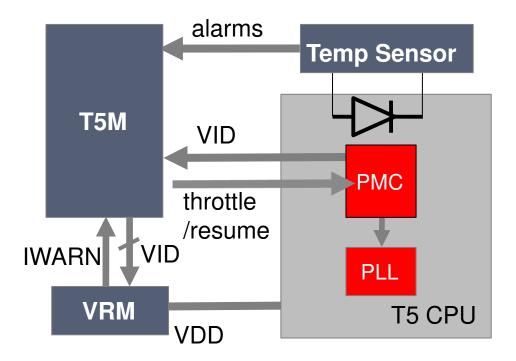
- Link scaling (4,3,2,1 dynamically as needed)
 - Hardware monitors link utilization
 - Software sets entry exit policy (thresholds and dwell times)



Memory Link Power Savings

- Two-levels of memory link standby
 - -L0s: Power savings with fast wake up
 - Light sleep for N frames, then wake up and listen for data
 - -L1: Much more power savings with longer wake up
 - Completely power off both tx and rx except for PLL
 - Used for unallocated memory regions

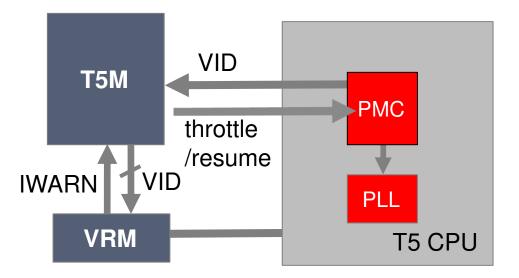
Peak Performance Thermal Management



- 4 thermal diodes per chip
 - centered in core quads
- If any T > high-water mark
 Drop Freq, V
- If all T < low-water mark Raise Freq, V

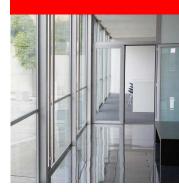
Peak Performance Current Management

- Drop F,V if any current
 > high-water mark
- Raise F,V if any current < low-water mark
- Controls currents for CPU VDD plus motherboard and DIMMs



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T5 PCIe Subsystem

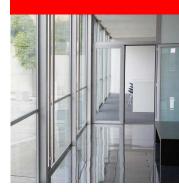
- Dual x8 PCI Express Gen 3 ports provide 32 GB/s peak b/w
- Supports Atomic Fetch-and-Add, Unconditional-Swap and Compare-and-Swap operations
- Accelerates virtualized I/O with Oracle Solaris VMs
 - 128k virtual function address spaces ensure direct SR-IOV access for all logical domains
 - 64-bit DVMA space reduces IO mapping overhead, improving network performance
 - Guarantees fault and performance isolation among guest OS instances
- Supports PCI Express Power Management

T5 PCIe Progression

	Τ4	Т5
PCI Express revision	Gen 2 (dual x8 ports)	Gen 3 (dual x8 ports)
Throughput full duplex	16 GBs	32 GBs
Data Management Unit	Single shared unit for both x8 PCIe ports	Two independent units one for each x8 PCIe port
Physical Address Support	44 bit	48 bit
Transaction Id Identification on MSI and MSI-X	No	Yes
PCIe Atomic Transactions	No	Yes
TLP Processing Hints	No	Yes, directs data to L3 cache
PCIe 2.0 compliance (ECN "Internal Error Reporting")	Signaled via MSI interrupt	Signaled via PCIe message

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SPARC T5 Summary

- Processor provides
 - Leadership throughput and per-thread performance
 - The industry's best on-chip encryption acceleration
 - Advanced power management
 - Highly-efficient one hop glueless scalability to 8 sockets
 - Enterprise-class general purpose computing and RAS
- SPARC T5 is the world's best processor for running Oracle software
 - Oracle Database, Fusion Applications, Fusion Middleware

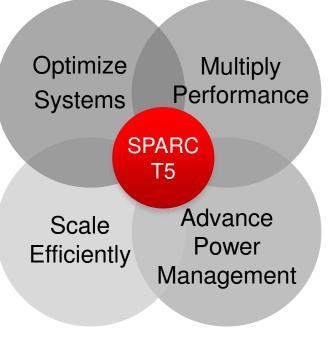
Design Objectives Achieved

- Oracle workloads
- Engineered Systems

 Extends

 ✓ on-chip crypto acceleration
 ✓ RAS

- Scales to 8 sockets using directory
- Minimizes latency
- Avoids congestion
- Maximize bandwidth



- Double cores and cache
- Balance single thread and throughput
- Dynamically thread
- Maximizes peak
 performance
- Manages thermal and current loads
- Scales elastically





Hardware and Software

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Engineered to Work Together



